

## General Description

This PAN00SF94GF N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

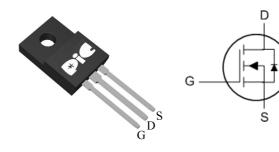
### Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent Cdv /dt effect decline
- Advanced high cell density Trenchtechnology

# Application

- SMPS Power Supplier
- Charger Adapter
- Power Tools
- LED Lighting

### > TO220F



## Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current <sup>1</sup>	I⊳@Tc=25°C	36	А
Continuous Drain Current <sup>1</sup>	I <sub>D</sub> @T <sub>C</sub> =100°C	25	А
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	120	А
Single Pulse Avalanche Energy <sup>3</sup>	EAS	33	mJ
Avalanche Current	I <sub>AS</sub>	15	А
Total Power Dissipation <sup>4</sup>	P <sub>D</sub> @T <sub>C</sub> =25°C	56.5	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	TJ	-55 to 150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	ReJA	60	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	Rejc	4.5	°C/W



# N-Ch 100V Fast Switching MOSFET V<sub>DS</sub>=100V, I<sub>D</sub>=36A ,RDS<sub>(ON)</sub>=12mΩ

## Electrical Characteristics (T<sub>J</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V	
Static Drain-Source On-Resistance <sup>2</sup>	Process	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		8.5	12	mΩ	
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		12	15	11152	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2		2.4	V	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	1 uA	
Drain Godiec Edakage Garrent	יטסט	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
Total Gate Charge (10V)	Qg			43			
Total Gate Charge (4.5V)	Qg	VDS=50V, VGS=10V, ID=20A		18.5		nC	
Gate-Source Charge	Qgs	7 VD3-30V , VG3-10V , ID-20A		8.5			
Gate-Drain Charge	Qgd	]		10.3			
Turn-On Delay Time	Td(on)			10			
Rise Time	Tr	$V$ DD=50 $V$ , $V$ GS=10 $V$ , $R$ G=3.3 $\Omega$		7		ns	
Turn-Off Delay Time	Td(off)	ID=20A		50			
Fall Time	Tf	1		11		1	
Input Capacitance	Ciss			3150			
Output Capacitance	Coss	VDS=50V , VGS=0V , f=1MHz		695		pF	
Reverse Transfer Capacitance	Crss	]		25		1	

### Diode Characteristics

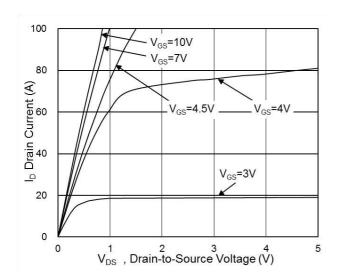
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous Source Current <sup>1,5</sup>	Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			36	Α
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V
Reverse Recovery Time	t <sub>rr</sub>	IF=20A, di/dt=100A/µs,		45		nS
Reverse Recovery Charge	Qrr	TJ=25°C		165		nC

#### Note:

- 1. Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.3mH,  $I_{AS}$ =15A
- 4.Ensure that the channel temperature does not exceed 150°C.
- 5.The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



### > Typical Characteristics



**Fig.1 Typical Output Characteristics** 

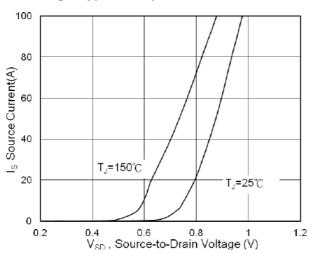


Fig.3 Source Drain Forward Characteristics

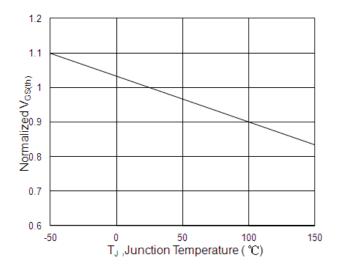


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$ 

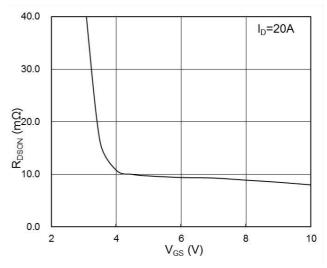


Fig.2 On-Resistance vs G-S Voltage

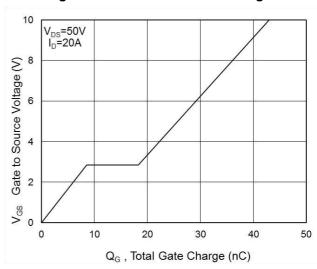


Fig.4 Gate-Charge Characteristics

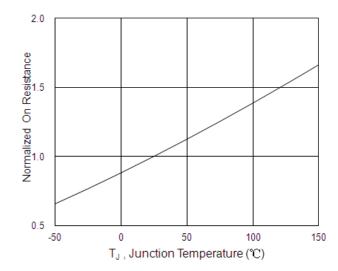
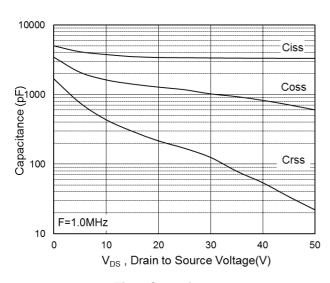


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>





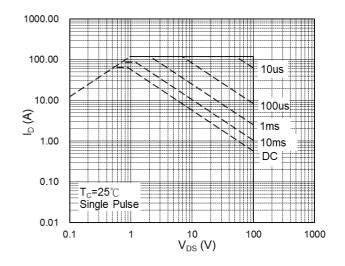


Fig.7 Capacitance

Fig.8 Safe Operating Area

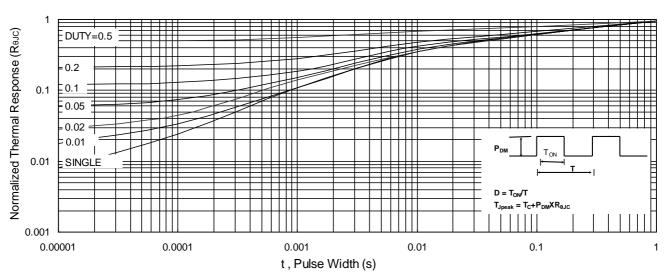


Fig.9 Normalized Maximum Transient Thermal Impedance

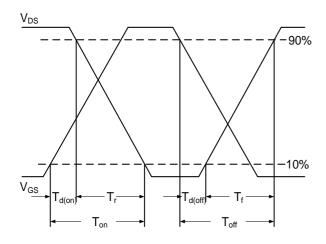


Fig.10 Switching Time Waveform

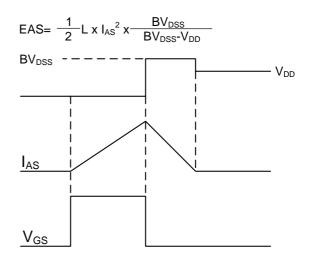
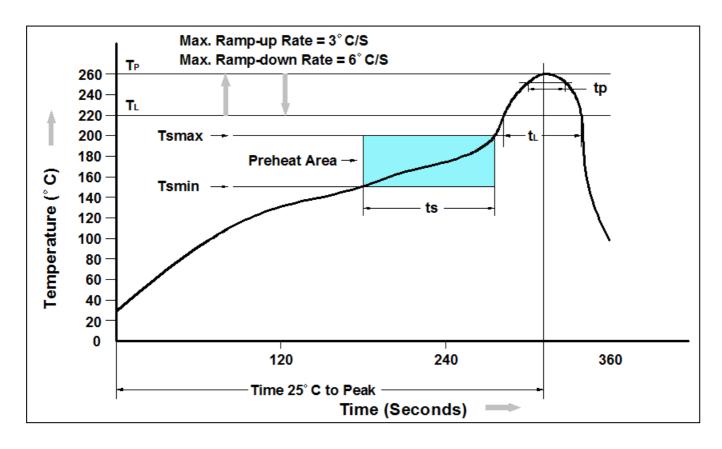


Fig.11 Unclamped Inductive Switching Waveform



# Recommand IR Reflow Soldering Thermal Profile



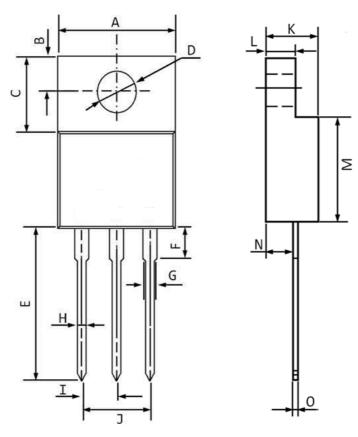
Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C /-5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

# Ordering Information

Part Number	Description	Quantity
PAN00SF94GF	TO-220F / 50 pcs/tube	1000 pcs



# Package Information (TO-220F)



SYMBOLS	MILLIMETERS		INCHES		
STWIDOLS	Min.	Max.	Min.	Max.	
Α		10.50		0.414	
В	2.60	3.00	0.102	0.118	
С	6.70	7.10	0.264	0.280	
D	2.90	3.50	0.114	0.138	
E	13.10	13.90	0.516	0.548	
F		4.00		0.158	
G	1.11	1.45	0.044	0.057	
Н	0.40	0.80	0.016	0.032	
1	2.40	2.80	0.095	0.110	
J	5.00	5.40	0.197	0.213	
K	4.30	4.70	0.169	0.185	
L	2.90	3.30	0.114	0.130	
M	8.20	9.00	0.323	0.355	
N	2.50	2.90	0.099	0.114	
0	0.40	0.80	0.016	0.032	

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